

L Number	Hits	Search Text	DB	Time stamp
-	37	Towle-Steven\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:13
-	6	George-Anna\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:13
-	9	Lu-Daoqiang\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:16
-	1556	((flip adj chip) (flip-chip)) near6 ((active adj area) element)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:33
-	402	waveguide same (substrate and ((flip adj chip) flip-chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:34
-	5276	((flip adj chip) (flip-chip)) near6 solder\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:49
-	38	optical adj solder\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:31
-	0	((flip adj chip) (flip-chip)) near6 ((active adj area) element)) and (waveguide same (substrate and ((flip adj chip) flip-chip))) and (((flip adj chip) (flip-chip)) near6 solder\$3) and (optical adj solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:22
-	11	((flip adj chip) (flip-chip)) near6 ((active adj area) element)) and (waveguide same (substrate and ((flip adj chip) flip-chip))) and (((flip adj chip) (flip-chip)) near6 solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:22
-	38	(optical adj solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 13:34
-	3	((flip adj chip) (flip-chip)) same (optical near solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 13:50
-	32511	substrate same waveguide	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 14:38
-	370	(substrate same waveguide) and ((flip-chip (flip adj chip) optoelectronic) same solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:16
-	110	(substrate same waveguide) and (solder\$3 near5 (protect\$4 guard\$3 shield\$3 cover\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 16:24
-	31	((substrate same waveguide) and ((flip-chip (flip adj chip) optoelectronic) same solder\$3)) and ((substrate same waveguide) and (solder\$3 near5 (protect\$4 guard\$3 shield\$3 cover\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 14:47

-	7	((substrate same waveguide) and ((flip-chip (flip adj chip) optoelectronic) same solder\$3)) and ((substrate same waveguide) and (solder\$3 near5 (protect\$4 guard\$3 shield\$3 cover\$4)))) and 385/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 14:47
-	246	(substrate same waveguide) and (optical\$3 near3 solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:15
-	11	(substrate same waveguide) and ((flip-chip (flip adj chip) optoelectronic) same (optical\$3 near3 solder\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:16
-	32511	waveguide same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 16:44
-	44	(flip-chip (flip adj chip) optoelectronic) near9 (optica\$3 near3 solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:25
-	5	(waveguide same substrate) and ((flip-chip (flip adj chip) optoelectronic) near9 (optica\$3 near3 solder\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:20
-	6328	(flip-chip (flip adj chip) optoelectronic) near9 (solder\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 16:43
-	212	(waveguide same substrate) and ((flip-chip (flip adj chip) optoelectronic) near9 (solder\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:25
-	104	((waveguide same substrate) and ((flip-chip (flip adj chip) optoelectronic) near9 (solder\$3))) and 385/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 15:26
-	2852	(flip-chip (flip adj chip) optoelectronic) with active	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 17:35
-	945	((flip-chip (flip adj chip) optoelectronic) near9 (solder\$3)) and ((flip-chip (flip adj chip) optoelectronic) with active)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 16:43
-	65	((flip-chip (flip adj chip) optoelectronic) near9 (solder\$3)) and ((flip-chip (flip adj chip) optoelectronic) with active)) and (waveguide same substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 16:51
-	140	(optic\$4 near4 solder\$3) with (protect\$3 guard\$4 defend\$4 cover\$3 shield\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 17:51
-	21	((optic\$4 near4 solder\$3) with (protect\$3 guard\$4 defend\$4 cover\$3 shield\$3)) and ((flip-chip (flip adj chip) optoelectronic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 17:36
-	7	(optic\$4 near solder\$3) with (protect\$3 guard\$4 defend\$4 cover\$3 shield\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 19:05
-	427	(substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))	USPAT; US-PGPUB	2004/09/17 10:34

-	33600	(chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate)	USPAT; US-PGPUB	2004/09/16 20:10
-	112	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 10:37
-	288	(chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4	EPO; JPO; DERWENT	2004/09/16 20:10
-	88	(substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))	EPO; JPO; DERWENT	2004/09/16 20:10
-	17276	(chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate)	EPO; JPO; DERWENT	2004/09/16 20:10
-	6	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))	EPO; JPO; DERWENT	2004/09/16 20:10
-	36	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) same ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 20:13
-	76	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) same ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 20:16
-	54	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) same ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))) not (((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) same ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 20:18
-	49	((chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same (waveguide (wave near guide))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same (waveguide (wave near guide) substrate))) and 385/14,31,51,52,129,130.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 20:20
-	57608	(waveguide fiber) same substrate	USPAT; US-PGPUB	2004/09/17 10:07
-	4959	(optoelectronic opto-electronic (flip-chip) (flip adj chip)) near8 solder\$3	USPAT; US-PGPUB	2004/09/17 10:06
-	812	(optoelectronic opto-electronic (flip-chip) (flip adj chip)) near7 coupl\$4 near7 (waveguide fiber)	USPAT; US-PGPUB	2004/09/17 10:07
-	86	((waveguide fiber) same substrate) and ((optoelectronic opto-electronic (flip-chip) (flip adj chip)) near8 solder\$3) and ((optoelectronic opto-electronic (flip-chip) (flip adj chip)) near7 coupl\$4 near7 (waveguide fiber))	USPAT; US-PGPUB	2004/09/17 10:13
-	130	(active near3 (area region)) near5 solder\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 10:25
-	33	((active near3 (area region)) near5 solder\$3) and (waveguide fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 10:25

-	847	(chip IC (integrated adj circuit)) near12 (waveguide (wave near guide)) near7 coupl\$4	USPAT; US-PGPUB	2004/09/17 10:36
-	83	((chip IC (integrated adj circuit)) near12 (fiber) near7 coupl\$4) and ((substrate material) near7 coupl\$4 same (chip IC (integrated adj circuit)) same ((fiber))) and ((chip IC (integrated adj circuit)) near12 (contact\$4 electric\$4 solder\$3) same ((fiber) substrate))	USPAT; US-PGPUB	2004/09/17 10:53
-	2569	385/88,92,94.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 13:34
-	2451	385/88,92,94.ccls. and (waveguide fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 13:35
-	201	385/88,92,94.ccls. and ((chip IC (integrated adj circuit) opto-electronic (flip-chip) (flip adj chip)) near6 coupl\$4 near6 (waveguide fiber))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/17 13:42